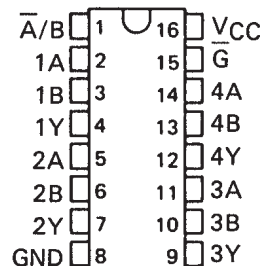


SN54LS257B, SN54LS258B, SN54S257, SN54S258 SN74LS257B, SN74LS258B, SN74S257, SN74S258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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- Three-State Outputs Interface Directly with System Bus
- 'LS257B and 'LS258B Offer Three Times the Sink-Current Capability of the Original 'LS257 and 'LS258
- Same Pin Assignments as SN54LS157, SN74LS157, SN54S157, SN74S157, and SN54LS158, SN74LS158, SN54S158, SN74S158
- Provides Bus Interface from Multiple Sources in High-Performance Systems

SN54LS257B, SN54S257,
SN54LS258B, SN54S258 . . . J OR W PACKAGE
SN74LS257B, SN74S257,
SN74LS258B, SN74S258 . . . D OR N PACKAGE
(TOP VIEW)



	AVERAGE PROPAGATION DELAY FROM DATA INPUT	TYPICAL POWER DISSIPATION†
'LS257B	9 ns	55 mW
'LS258B	9 ns	55 mW
'S257	4.8 ns	320 mW
'S258	4 ns	280 mW

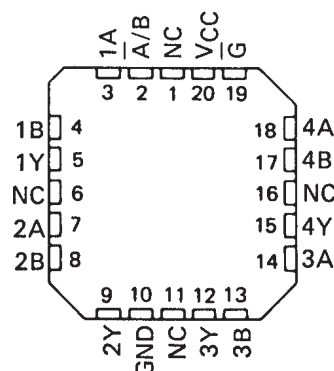
† Off state (worst case)

description

These devices are designed to multiplex signals from four-bit data sources to four-output data lines in bus-organized systems. The 3-state outputs will not load the data lines when the output control pin (\bar{G}) is at a high-logic level.

Series 54LS and 54S are characterized for operation over the full military temperature range of -55°C to 125°C ; Series 74LS and 74S are characterized for operation from 0°C to 70°C .

SN54LS257B, SN54S257,
SN54LS258B, SN54S258 . . . FK PACKAGE
(TOP VIEW)



NC-No internal connection.

FUNCTION TABLE

INPUTS				OUTPUT Y	
OUTPUT CONTROL	SELECT	A	B	'LS257B 'S257	'LS258B 'S258
H	X	X	X	Z	Z
L	L	L	X	L	H
L	L	H	X	H	L
L	H	X	L	L	H
L	H	X	H	H	L

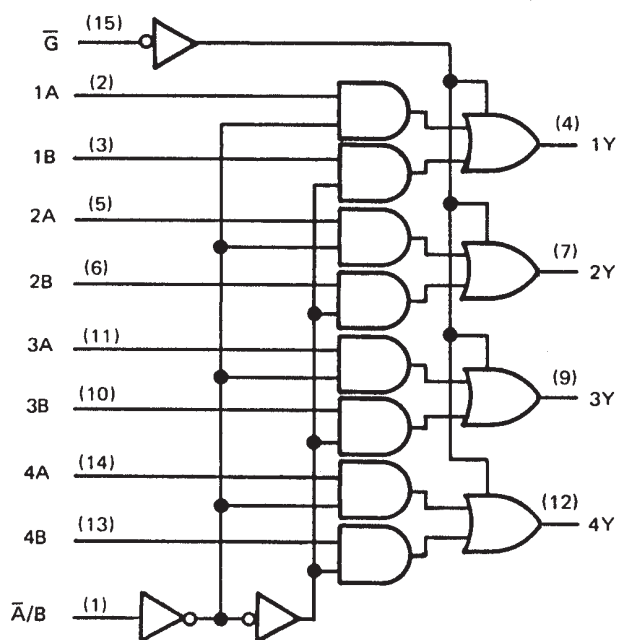
H = high level, L = low level, X = irrelevant,
Z = high impedance (off)

SN54LS257B, SN54LS258B, SN54S257, SN54S258
 SN74LS257B, SN74LS258B, SN74S257, SN74S258
 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

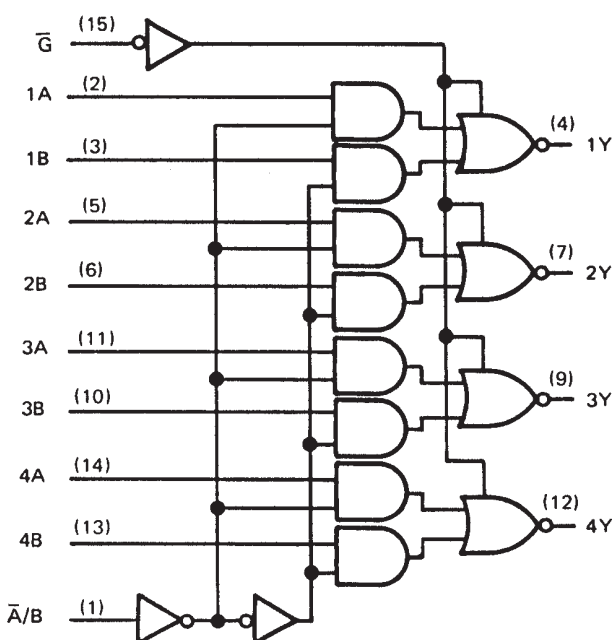
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logic diagrams (positive logic)

'LS257B, 'S257

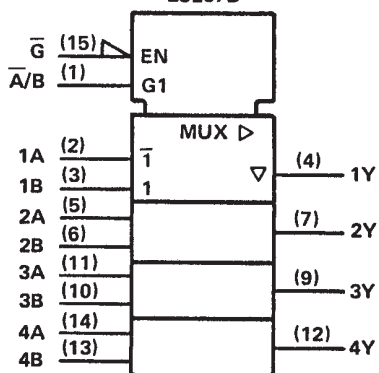


'LS258B, 'S258

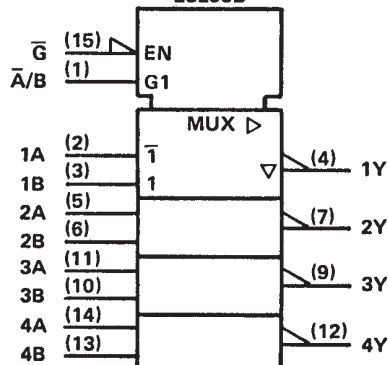


logic symbols†

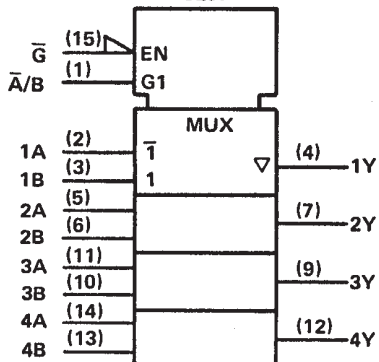
'LS257B



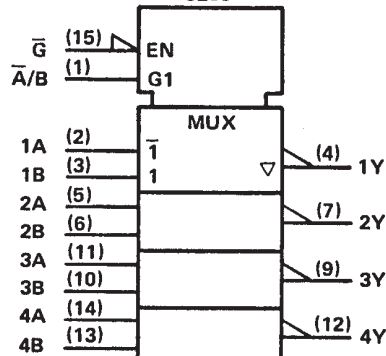
'LS258B



'S257



'S258

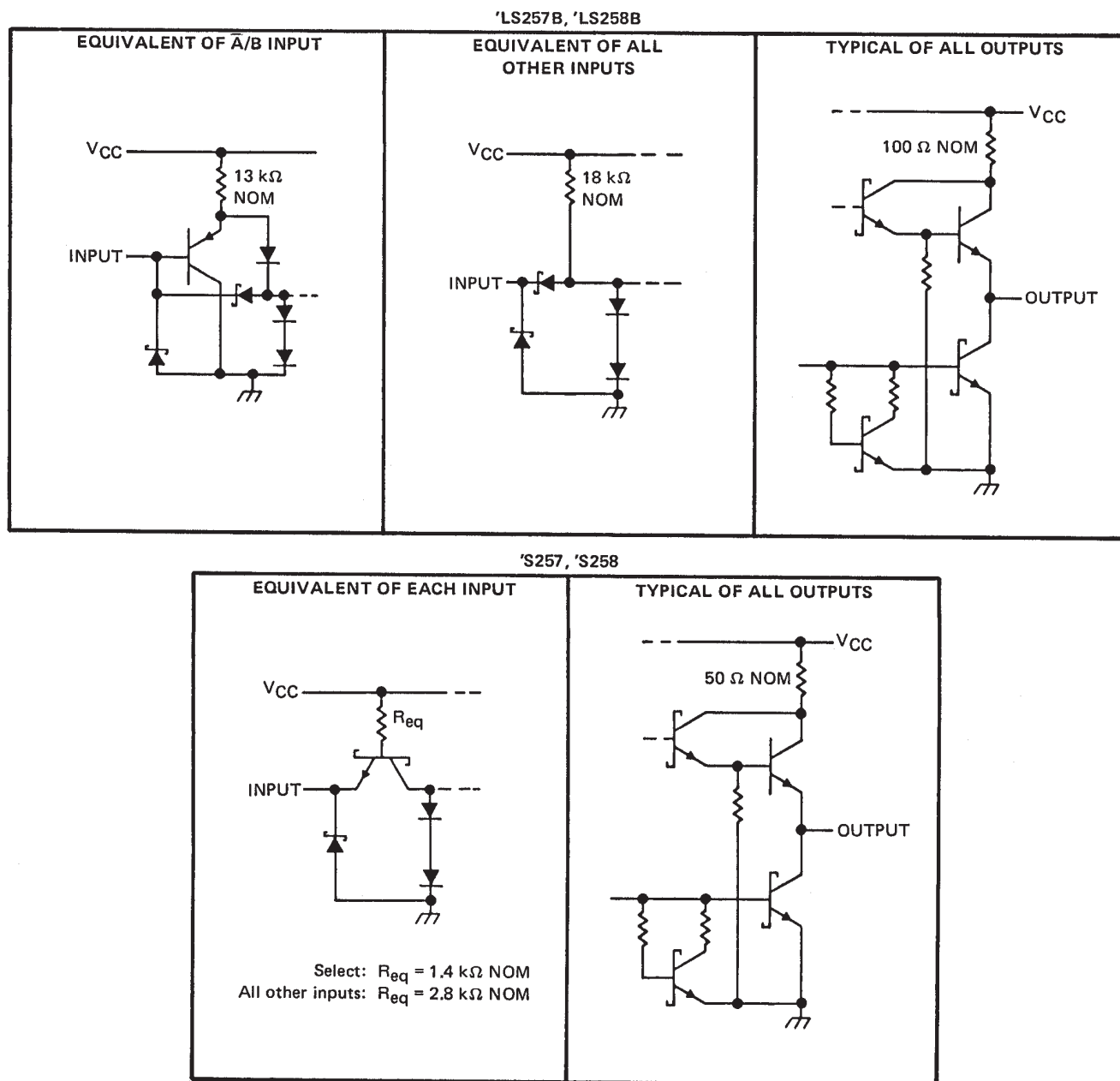


†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
 Pin numbers shown are for D, J, N, and W packages.

SN54LS257B, SN54LS258B, SN54S257, SN54S258
SN74LS257B, SN74LS258B, SN74S257, SN74S258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage: 'LS257B, 'LS258B Circuits	7 V
'S257, 'S258 Circuits	5.5 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54LS', SN54S' Circuits	-55°C to 125°C
SN74LS', SN74S' Circuits	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54LS257B, SN54LS258B, SN54S257, SN54S258
SN74LS257B, SN74LS258B, SN74S257, SN74S258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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recommended operating conditions

	SN54LS'			SN74LS'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.7			0.8	V
I _{OH} High-level output current			– 1			– 2.6	mA
I _{OL} Low-level output current			12			24	mA
T _A Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS'		SN74LS'		UNIT
				MIN	TYP‡	MAX	MIN	
V _{IK}		V _{CC} = MIN, I _I = – 18 mA		– 1.5		– 1.5		V
V _{OH}		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX, I _{OH} = MAX		2.4	3.4	2.4	3.1	V
V _{OL}		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = MAX,	I _{OL} = 12 mA	0.25	0.4	0.25	0.4	V
			I _{OL} = 24 mA			0.35	0.5	
I _{OZH}		V _{CC} = MAX, V _{IH} = 2 V, V _O = 2.7 V		20		20		μA
I _{OZL}		V _{CC} = MAX, V _{IH} = 2 V, V _O = 0.4 V		– 20		– 20		μA
I _I		V _{CC} = MAX, V _I = 7 V		0.1		0.1		mA
I _{IH}		V _{CC} = MAX, V _I = 2.7 V		20		20		μA
I _{IL}		V _{CC} = MAX, V _I = 0.4 V		– 0.4		– 0.4		mA
I _{OS} §		V _{CC} = MAX,		– 30	– 130	– 30	– 130	mA
I _{CC}	All outputs high	V _{CC} = MAX, See Note 2	'LS257B	8	12	8	12	mA
	All outputs low			12	18	12	18	
	All outputs off			13	19	13	19	
	All outputs high		'LS258B	6	9	6	9	
	All outputs low			10	15	10	15	
	All outputs off			11	16	11	16	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 2: I_{CC} is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

switching characteristics, V_{CC} = 5 V, T_A = 25°C, R_L = 667 Ω

PARAMETER ¹	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS257B			'LS258B			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t _{PLH}	Data	Any	C _L = 45 pF, See Note 3	8	13		7	12	ns	
t _{PHL}				10	15		11	17		
t _{PLH}	Select	Any		16	21		14	21	ns	
t _{PHL}				17	24		19	24		
t _{PZH}	Output Control	Any		15	30		15	30	ns	
t _{PZL}				19	30		20	30		
t _{PHZ}	Output Control	Any	C _L = 5 pF, See Note 3	18	30		18	30	ns	
t _{PLZ}			16	25		16	25			

¶ t_{PLH} = propagation delay time, low-to-high-level output

t_{PHL} = propagation delay time, high-to-low-level output

t_{PZH} = output enable time to high level

tp_{ZL} = output enable time to low level

t_{PHZ} = output disable time from high level

t_{PLZ} = output disable time from low level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



**SN54LS257B, SN54LS258B, SN54S257, SN54S258
SN74LS257B, SN74LS258B, SN74S257, SN74S258
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS**

SDLS148 – OCTOBER 1976 – REVISED MARCH 1988

recommended operating conditions

	SN54S'			SN74S'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			-2			-6.5	mA
Low-level output current, I_{OL}			20			20	mA
Operating free-air temperature, T_A	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†	'S257			'S258			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IH} High-level input voltage						2			V	
V _{IL} Low-level input voltage						0.8			V	
V _{IK} Input clamp voltage			V _{CC} = MIN, I _I = −18 mA			−1.2			V	
V _{OH} High-level output voltage			V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = −1 mA	SN74S'	2.7		2.7		V	
			V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = MAX	SN54S'	2.4	3.4	2.4	3.4		
				SN74S'	2.4	3.2	2.4	3.2		
V _{OL} Low-level output voltage			V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OL} = 20 mA			0.5		0.5	V	
I _{OZH} Off-state output current, high-level voltage applied			V _{CC} = MAX, V _{IH} = 2 V, V _O = 2.4 V			50		50	μA	
I _{OZL} Off-state output current, low-level voltage applied			V _{CC} = MAX, V _{IH} = 2 V, V _O = 0.5 V			−50		−50	μA	
I _I Input current at maximum input voltage			V _{CC} = MAX, V _I = 5.5 V			1		1	mA	
I _{IH} High-level input current		S input	V _{CC} = MAX, V _I = 2.7 V			100		100	μA	
		Any other				50		50		
I _{IL} Low-level input current		S input	V _{CC} = MAX V _I = 0.5 V			−4		−4	mA	
		Any other				−2		−2		
I _{OS} Short-circuit output current §			V _{CC} = MAX			−40 −100		−40 −100	mA	
I _{CC} Supply current		All outputs high	V _{CC} = MAX, See Note 2			44 68		36 56	mA	
		All outputs low				60 93		52 81		
		All outputs off				64 99		56 87		

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 2: I_{CC} is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}, R_L = 280 \Omega$

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'S257			'S258			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
tPLH	Data	Any	CL = 15 pF, See Note 3	5	7.5		4	6	ns	
tPHL				4.5	6.5		4	6		
tPLH	Select	Any		8.5	15		8	12	ns	
tPHL				8.5	15		7.5	12		
tPZH	Output	Any		13	19.5		13	19.5	ns	
tPZL	Control			14	21		14	21		
tPHZ	Output	Any	CL = 5 pF, See Note 3	5.5	8.5		5.5	8.5	ns	
tPLZ	Control		9	14		9	14			

¶ f_{max} = Maximum clock frequency

t_{PLH} = propagation delay time, low-to-high-level output

t_{PHL} = propagation delay time, high-to-low-level output

t_{PZH} = output enable time to high level

t_{PZL} = output enable time to low level

t_{PHZ} = output disable time from high level

t_{PLZ} = output disable time from low level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-7603701VEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	
5962-7603701VFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	
5962-7603701VFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	
7603701EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
7603701EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
7603701FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
7603701FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
76038012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
76038012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
7603801EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
7603801EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
7603801FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
7603801FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
8002301EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
8002301EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
8002301FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
8002301FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Call TI	
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/07906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/07906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
JM38510/30906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
M38510/07906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/07906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/07906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
M38510/07906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
M38510/30906B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/30906B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/30906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/30906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
M38510/30906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
M38510/30906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SN54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SN74LS257BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LS257BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS257BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS257BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS257BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS257BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS257BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS257BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LS258BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS258BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS258BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS258BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS258BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74LS258BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS258BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S257N	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S257N	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S257N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74S257N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74S257NE4	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S257NE4	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74S258DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	
SN74S258DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	
SN74S258N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74S258N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74S258N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SN74S258N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	
SNJ54LS257BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SNJ54LS257BFB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS257BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS257BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS258BFB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS258BFB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS258BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54LS258BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S257FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S257FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S257W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S257W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S258FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S258FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S258W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	
SNJ54S258W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54LS257B, SN54LS257B-SP, SN54LS258B, SN54S257, SN54S258, SN74LS257B, SN74LS258B, SN74S257, SN74S258 :

- Catalog: [SN74LS257B](#), [SN54LS257B](#), [SN74LS258B](#), [SN74S257](#), [SN74S258](#)
- Military: [SN54LS257B](#), [SN54LS258B](#), [SN54S257](#), [SN54S258](#)
- Space: [SN54LS257B-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS257BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS257BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS258BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS257BDR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS257BNSR	SO	NS	16	2000	367.0	367.0	38.0
SN74LS258BDR	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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